Appln. No.: 10/720,420

Amendment Dated May 17, 2007

Reply to Office Action of January 17, 2007

NTP-116US

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## Remarks/Arguments:

Claims 1, 2, 4, 6, 8, and 9 are pending in this application.

Claims 1, 2, 4, 6, 8, and 9 have been rejected under 35 U.S.C. §102(e) as anticipated by Yamazaki et al. (US 6,849,877). Applicants respectfully submit that this rejection is overcome for the reason set forth below.

Yamazaki et al. disclose a light emitting device including an OLED formed on a plastic substrate, which can prevent the degradation due to penetration of moisture or oxygen. See Abstract. Yamazaki et al. deposit barrier films 111a and 111b on a second substrate 110, which may be a thick organic material. These layers are then bonded over the pixel elements using second bonding layer 109. The resulting device is illustrated in Figure 1C and the formation of these layers is described in column 5, lines 37-48 of the specification.

Yamazaki et al. do not disclose or suggest at least one feature recited in claim 1, as amended, namely:

...an encapsulation layer <u>formed directly on</u> at least one of <u>the anode</u> <u>layer</u>, the <u>cathode layer</u>, or the transparent <u>substrate</u>;... (Emphasis added)

Support for this feature of the present invention may be found in Figure 1 (where the encapsulation layer is shown as element 21) and in the exemplary methods beginning of page 12 of the specification. In exemplary devices of the present invention, the alternating polymer layers 211 and ceramic layers 212 of encapsulation layer 21 are deposited directly on an electrode of the OLED elements and/or on the back surface of substrate 11. Then, thick organic layer 22 is formed directly over the encapsulation layers, as described in the exemplary methods beginning of page 12 of the specification.

However, the formation of the device in Yamazaki et al. is different than devices of the present invention, which leads to a different structure. Because Yamazaki et al. deposit barrier films 111a and 111b on a second substrate 110, these layers must be bonded over the pixel elements using second bonding layer 109. Yamazaki et al. do not teach or suggest that the barrier film may be "formed directly on one side or both sides of the device," as recited in claim 1, as amended.

In view of this deficiency, Applicants respectfully submit that claim 1, as amended, is not subject to rejection under 35 U.S.C. §102(e) as being anticipated by Yamazaki et al. As claims 2, 4, 6, 8, and 9 depend from claim 1, these claims also are not subject to this rejection as well.

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## Conclusion

In view of the foregoing amendments and remarks, Applicants request that the Examiner reconsider and withdraw the rejections of claims 1, 2, 4, 6, 8, and 9.

Respectfully submitted,

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Dated: May 17, 2007

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The Director is hereby authorized to charge or credit Deposit Account No. 18-0350 for any additional fees, or any underpayment or credit for overpayment in connection herewith.

I hereby certify that this correspondence is being sent VIA FACSIMILE to 571-273-8300, in an envelope addressed to: MAIL STOP Amendment, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450 on: May 17, 2007

Kathleen Spina

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